



# SOT226

plastic single-ended package (I2PAK); TO-262

8 February 2016

Package information

## 1. Package summary

Terminal position code	S (single)
Package type descriptive code	I2PAK
Package type industry code	I2PAK
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	TO-262
Mounting method type	T (through-hole mount)
Issue date	25-8-2009

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		[tbd]	-	11	11	mm
E	package width		9.7	-	10	10.3	mm
A	seated height		4.1	-	4.3	4.5	mm
e	nominal pitch		-	-	2.54	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	3	-	



2. Package outline

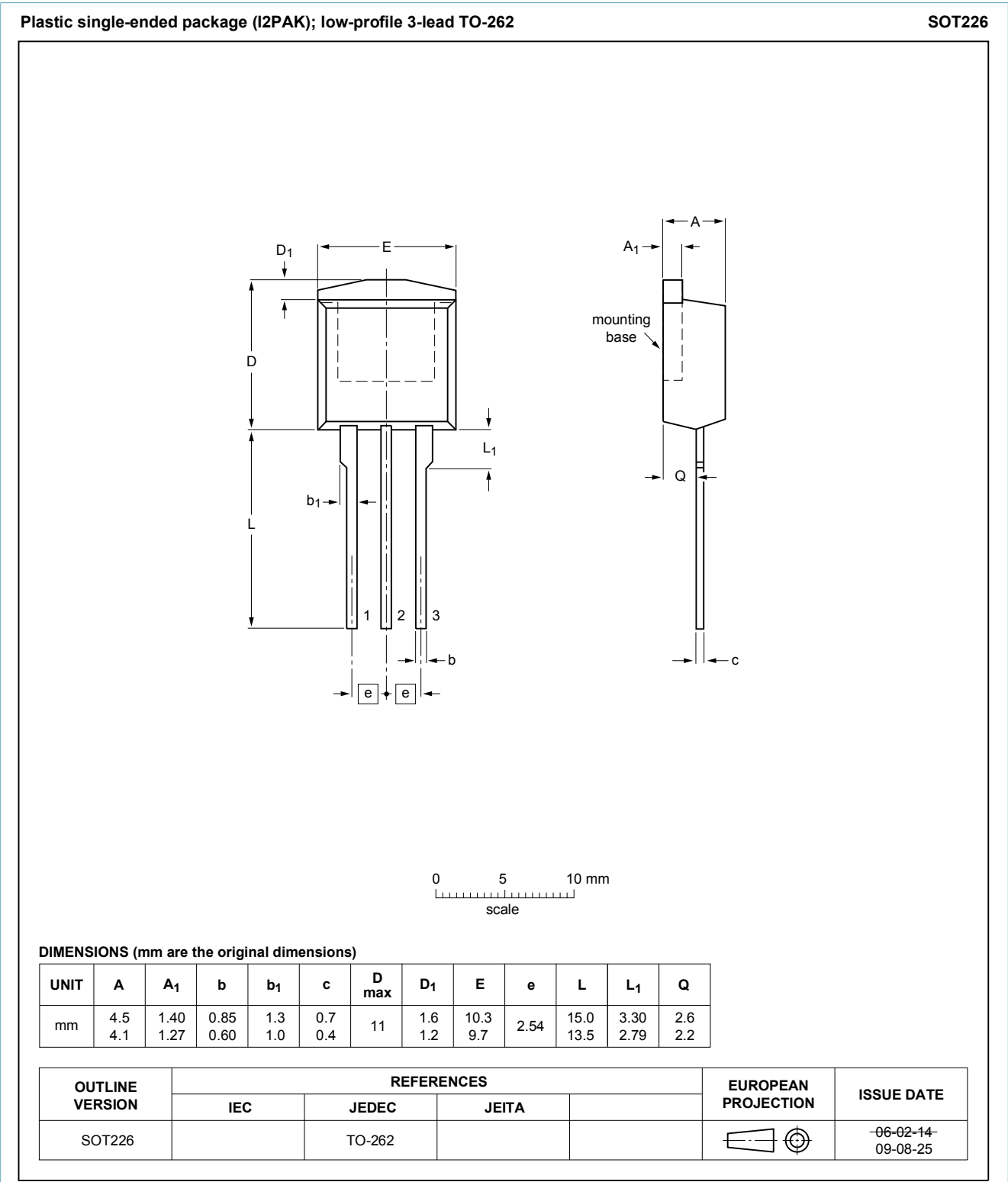


Fig. 1. Package outline I2PAK (SOT226)

### 3. Legal information

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